ABSTRACT

INTEGRATED CIRCUIT PACKAGE SYSTEM WITH HEAT SLUG

An integrated circuit package system is provided including providing a substrate having a die attached and electrically bonded thereto. The system includes forming heat slug pillars on the substrate, positioning a heat slug on the heat slug pillars, and encapsulating the substrate, the die, the heat slug pillars, and the heat slug in a mold compound. The system includes singulating the substrate, the die, the heat slug, and the mold compound.

(Fig. 2)